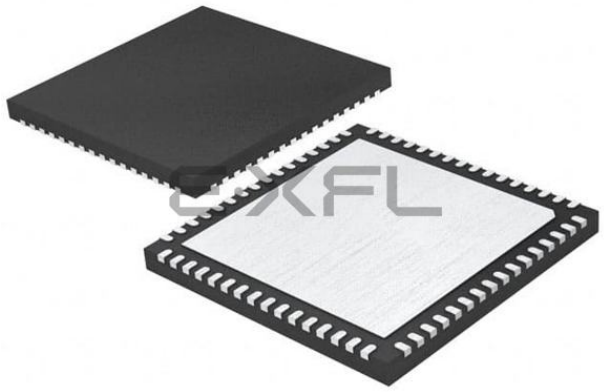

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	80MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	49
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 28x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VFQFN Exposed Pad
Supplier Device Package	64-VQFN (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx450f128h-v-mr

TABLE 1-1: PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number			Pin Type	Buffer Type	Description
	64-pin QFN/ TQFP	100-pin TQFP	124-pin VTLA			
CVREF-	15	28	A21	I	Analog	Comparator Voltage Reference (Low)
CVREF+	16	29	B17	I	Analog	Comparator Voltage Reference (High)
CVREFOUT	23	34	A24	I	Analog	Comparator Voltage Reference (Output)
C1INA	11	20	A12	I	Analog	Comparator 1 Inputs
C1INB	12	21	B11	I	Analog	
C1INC	5	11	B6	I	Analog	
C1IND	4	10	A7	I	Analog	
C2INA	13	22	A13	I	Analog	Comparator 2 Inputs
C2INB	14	23	B13	I	Analog	
C2INC	8	14	A9	I	Analog	
C2IND	6	12	A8	I	Analog	
C1OUT	PPS	PPS	PPS	O	—	Comparator 1 Output
C2OUT	PPS	PPS	PPS	O	—	Comparator 2 Output
PMALL	30	44	A29	O	TTL/ST	Parallel Master Port Address Latch Enable Low Byte
PMALH	29	43	B24	O	TTL/ST	Parallel Master Port Address Latch Enable High Byte
PMA0	30	44	A29	O	TTL/ST	Parallel Master Port Address bit 0 Input (Buffered Slave modes) and Output (Master modes)
PMA1	29	43	B24	O	TTL/ST	Parallel Master Port Address bit 0 Input (Buffered Slave modes) and Output (Master modes)
PMA2	8	14	A9	O	TTL/ST	Parallel Master Port data (Demultiplexed Master mode) or Address/Data (Multiplexed Master modes)
PMA3	6	12	A8	O	TTL/ST	
PMA4	5	11	B6	O	TTL/ST	
PMA5	4	10	A7	O	TTL/ST	
PMA6	16	29	B17	O	TTL/ST	
PMA7	22	28	A21	O	TTL/ST	
PMA8	32	50	A32	O	TTL/ST	
PMA9	31	49	B27	O	TTL/ST	
PMA10	28	42	A28	O	TTL/ST	
PMA11	27	41	B23	O	TTL/ST	
PMA12	24	35	B20	O	TTL/ST	
PMA13	23	34	A24	O	TTL/ST	
PMA14	45	71	A46	O	TTL/ST	
PMA15	44	70	B38	O	TTL/ST	
PMCS1	45	71	A46	O	TTL/ST	
PMCS2	44	70	B38	O	TTL/ST	
PMD0	60	93	B52	I/O	TTL/ST	
PMD1	61	94	A64	I/O	TTL/ST	
PMD2	62	98	A66	I/O	TTL/ST	

Legend: CMOS = CMOS compatible input or output
ST = Schmitt Trigger input with CMOS levels
TTL = TTL input buffer
Analog = Analog input
O = Output
P = Power
I = Input

Note 1: This pin is only available on devices without a USB module.
2: This pin is only available on devices with a USB module.
3: This pin is not available on 64-pin devices.

NOTES:

3.2 Architecture Overview

The MIPS32® M4K® processor core contains several logic blocks working together in parallel, providing an efficient high-performance computing engine. The following blocks are included with the core:

- Execution Unit
- Multiply/Divide Unit (MDU)
- System Control Coprocessor (CP0)
- Fixed Mapping Translation (FMT)
- Dual Internal Bus interfaces
- Power Management
- MIPS16e® Support
- Enhanced JTAG (EJTAG) Controller

3.2.1 EXECUTION UNIT

The MIPS32® M4K® processor core execution unit implements a load/store architecture with single-cycle ALU operations (logical, shift, add, subtract) and an autonomous multiply/divide unit. The core contains thirty-two 32-bit General Purpose Registers (GPRs) used for integer operations and address calculation. One additional register file shadow set (containing thirty-two registers) is added to minimize context switching overhead during interrupt/exception processing. The register file consists of two read ports and one write port and is fully bypassed to minimize operation latency in the pipeline.

The execution unit includes:

- 32-bit adder used for calculating the data address
- Address unit for calculating the next instruction address
- Logic for branch determination and branch target address calculation
- Load aligner
- Bypass multiplexers used to avoid stalls when executing instruction streams where data producing instructions are followed closely by consumers of their results
- Leading Zero/One detect unit for implementing the `CLZ` and `CLO` instructions
- Arithmetic Logic Unit (ALU) for performing bitwise logical operations
- Shifter and store aligner

3.2.2 MULTIPLY/DIVIDE UNIT (MDU)

The MIPS32® M4K® processor core includes a Multiply/Divide Unit (MDU) that contains a separate pipeline for multiply and divide operations. This pipeline operates in parallel with the Integer Unit (IU) pipeline and does not stall when the IU pipeline stalls. This allows MDU operations to be partially masked by system stalls and/or other integer unit instructions.

The high-performance MDU consists of a 32x16 booth recoded multiplier, result/accumulation registers (HI and LO), a divide state machine, and the necessary multiplexers and control logic. The first number shown ('32' of 32x16) represents the *rs* operand. The second number ('16' of 32x16) represents the *rt* operand. The PIC32 core only checks the value of the latter (*rt)* operand to determine how many times the operation must pass through the multiplier. The 16x16 and 32x16 operations pass through the multiplier once. A 32x32 operation passes through the multiplier twice.

The MDU supports execution of one 16x16 or 32x16 multiply operation every clock cycle; 32x32 multiply operations can be issued every other clock cycle. Appropriate interlocks are implemented to stall the issuance of back-to-back 32x32 multiply operations. The multiply operand size is automatically determined by logic built into the MDU.

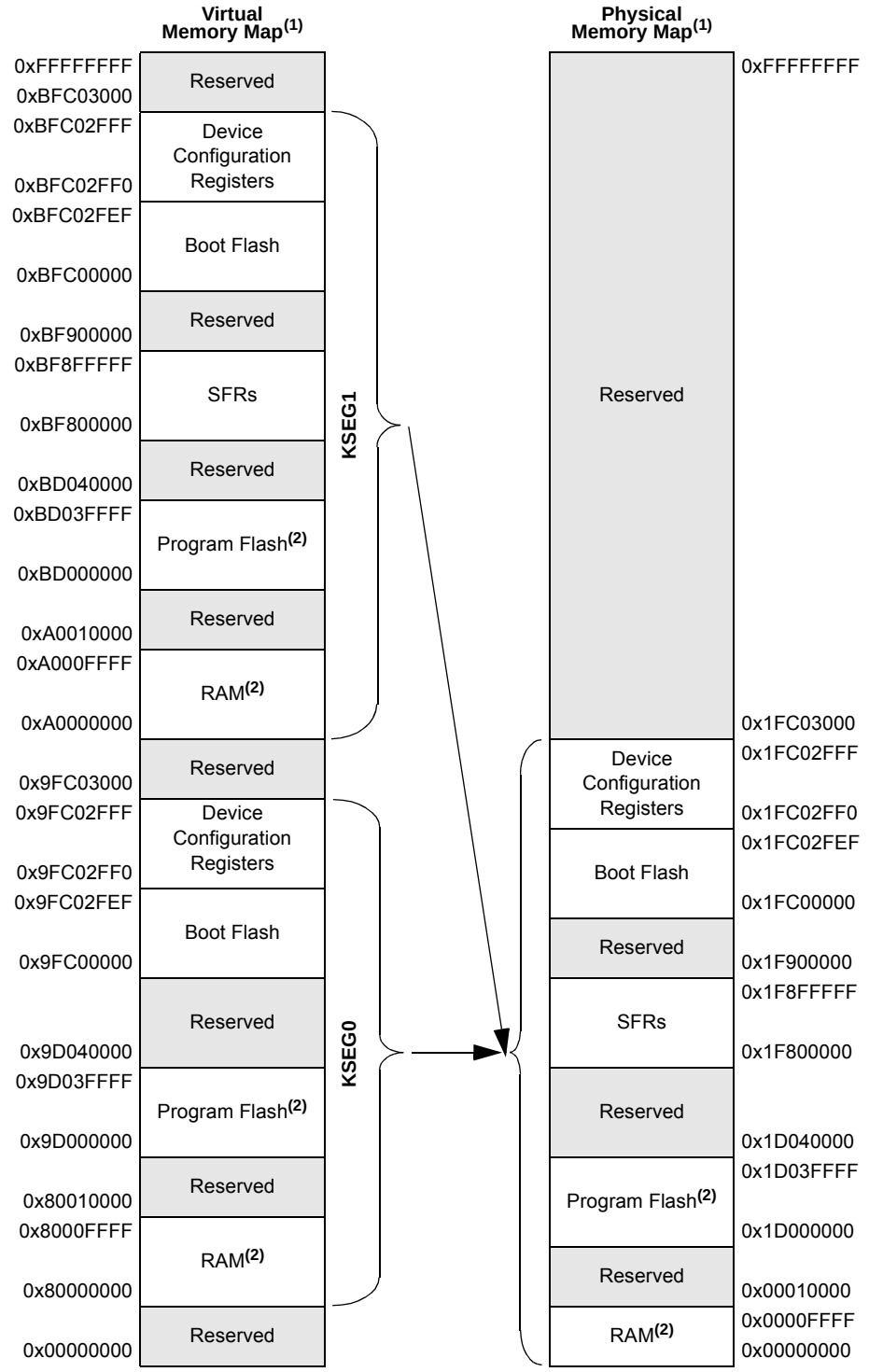
Divide operations are implemented with a simple 1 bit per clock iterative algorithm. An early-in detection checks the sign extension of the dividend (*rs*) operand. If *rs* is 8 bits wide, 23 iterations are skipped. For a 16-bit wide *rs*, 15 iterations are skipped and for a 24-bit wide *rs*, 7 iterations are skipped. Any attempt to issue a subsequent `MDU` instruction while a divide is still active causes an IU pipeline stall until the divide operation is completed.

Table 3-1 lists the repeat rate (peak issue rate of cycles until the operation can be reissued) and latency (number of cycles until a result is available) for the PIC32 core multiply and divide instructions. The approximate latency and repeat rates are listed in terms of pipeline clocks.

TABLE 3-1: MIPS32® M4K® PROCESSOR CORE HIGH-PERFORMANCE INTEGER MULTIPLY/ DIVIDE UNIT LATENCIES AND REPEAT RATES

Op code	Operand Size (mul *rt*) (div *rs*)	Latency	Repeat Rate
`MULT/MULTU, MADD/MADDU, MSUB/MSUBU`	16 bits	1	1
	32 bits	2	2
`MUL`	16 bits	2	1
	32 bits	3	2
`DIV/DIVU`	8 bits	12	11
	16 bits	19	18
	24 bits	26	25
	32 bits	33	32

FIGURE 4-3: MEMORY MAP FOR DEVICES WITH 256 KB OF PROGRAM MEMORY



Note 1: Memory areas are not shown to scale.

2: The size of this memory region is programmable (see **Section 3. "Memory Organization"** (DS60001115) in the *"PIC32 Family Reference Manual"*) and can be changed by initialization code provided by end-user development tools (refer to the specific development tool documentation for information).

REGISTER 4-3: BMXDUDBA: DATA RAM USER DATA BASE ADDRESS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R-0	R-0
	BMXDUDBA<15:8>							
7:0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
	BMXDUDBA<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15-10 **BMXDUDBA<15:10>:** DRM User Data Base Address bits

When non-zero, the value selects the relative base address for User mode data space in RAM, the value must be greater than BMXDKPBA.

bit 9-0 **BMXDUDBA<9:0>:** Read-Only bits

Value is always '0', which forces 1 KB increments

Note 1: At Reset, the value in this register is forced to zero, which causes all of the RAM to be allocated to Kernel mode data usage.

2: The value in this register must be less than or equal to BMXDRMSZ.

REGISTER 10-1: DMACON: DMA CONTROLLER CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	U-0	U-0	R/W-0	R/W-0	U-0	U-0	U-0
	ON(1)	—	—	SUSPEND	DMABUSY(1)	—	—	—
7:0	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15 **ON:** DMA On bit(1)
- 1 = DMA module is enabled
- 0 = DMA module is disabled

bit 14-13 **Unimplemented:** Read as '0'

bit 12 **SUSPEND:** DMA Suspend bit
- 1 = DMA transfers are suspended to allow CPU uninterrupted access to data bus
- 0 = DMA operates normally

bit 11 **DMABUSY:** DMA Module Busy bit(1)
- 1 = DMA module is active
- 0 = DMA module is disabled and not actively transferring data

bit 10-0 **Unimplemented:** Read as '0'

Note 1: When using 1:1 PBCLK divisor, the user's software should not read/write the peripheral's SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

REGISTER 10-9: DCHxINT: DMA CHANNEL 'x' INTERRUPT CONTROL REGISTER (CONTINUED)

bit 4 **CHDHIF:** Channel Destination Half Full Interrupt Flag bit
- 1 = Channel Destination Pointer has reached midpoint of destination (CHDPTR = CHDSIZ/2)
- 0 = No interrupt is pending

bit 3 **CHBCIF:** Channel Block Transfer Complete Interrupt Flag bit
- 1 = A block transfer has been completed (the larger of CHSSIZ/CHDSIZ bytes has been transferred), or a pattern match event occurs
- 0 = No interrupt is pending

bit 2 **CHCCIF:** Channel Cell Transfer Complete Interrupt Flag bit
- 1 = A cell transfer has been completed (CHCSIZ bytes have been transferred)
- 0 = No interrupt is pending

bit 1 **CHTAIF:** Channel Transfer Abort Interrupt Flag bit
- 1 = An interrupt matching CHAIRQ has been detected and the DMA transfer has been aborted
- 0 = No interrupt is pending

bit 0 **CHERIF:** Channel Address Error Interrupt Flag bit
- 1 = A channel address error has been detected
  Either the source or the destination address is invalid.
- 0 = No interrupt is pending

REGISTER 11-8: U1EIR: USB ERROR INTERRUPT STATUS REGISTER (CONTINUED)

bit 1 **CRC5EF:** CRC5 Host Error Flag bit(4)
1 = Token packet is rejected due to CRC5 error
0 = Token packet is accepted
EOFEF: EOF Error Flag bit(3,5)
1 = EOF error condition is detected
0 = No EOF error condition

bit 0 **PIDEF:** PID Check Failure Flag bit
1 = PID check is failed
0 = PID check is passed

Note 1: This type of error occurs when the module's request for the DMA bus is not granted in time to service the module's demand for memory, resulting in an overflow or underflow condition, and/or the allocated buffer size is not sufficient to store the received data packet causing it to be truncated.

2: This type of error occurs when more than 16-bit-times of Idle from the previous End-of-Packet (EOP) has elapsed.

3: This type of error occurs when the module is transmitting or receiving data and the SOF counter has reached zero.

4: Device mode.

5: Host mode.

REGISTER 11-16: U1SOF: USB SOF THRESHOLD REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CNT<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-8 **Unimplemented:** Read as '0'

bit 7-0 **CNT<7:0>:** SOF Threshold Value bits

Typical values of the threshold are:
01001010 = 64-byte packet
00101010 = 32-byte packet
00011010 = 16-byte packet
00010010 = 8-byte packet

REGISTER 11-17: U1BDTP1: USB BDT PAGE 1 REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0
	BDTPTRL<15:9>							—

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-8 **Unimplemented:** Read as '0'

bit 7-1 **BDTPTRL<15:9>:** BDT Base Address bits

This 7-bit value provides address bits 15 through 9 of the BDT base address, which defines the starting location of the BDT in system memory.

The 32-bit BDT base address is 512-byte aligned.

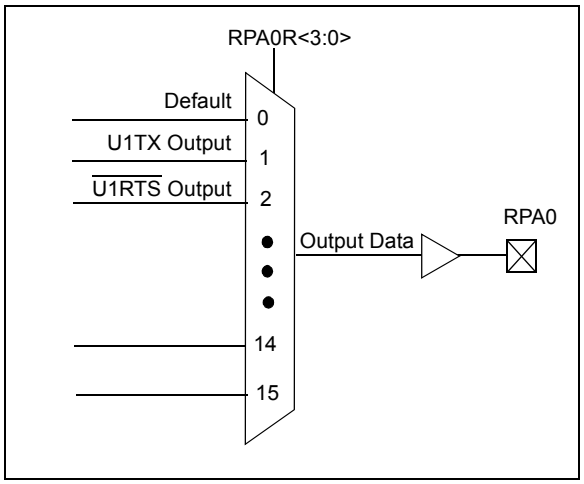
bit 0 **Unimplemented:** Read as '0'

12.3.5 OUTPUT MAPPING

In contrast to inputs, the outputs of the peripheral pin select options are mapped on the basis of the pin. In this case, a control register associated with a particular pin dictates the peripheral output to be mapped. The RPnR registers (Register 12-2) are used to control output mapping. Like the [*pin name*]R registers, each register contains sets of 4 bit fields. The value of the bit field corresponds to one of the peripherals, and that peripheral's output is mapped to the pin (see Table 12-2 and Figure 12-3).

A null output is associated with the output register reset value of '0'. This is done to ensure that remappable outputs remain disconnected from all output pins by default.

FIGURE 12-3: EXAMPLE OF MULTIPLEXING OF REMAPPABLE OUTPUT FOR RPA0



12.3.6 CONTROLLING CONFIGURATION CHANGES

Because peripheral remapping can be changed during run time, some restrictions on peripheral remapping are needed to prevent accidental configuration changes. PIC32 devices include two features to prevent alterations to the peripheral map:

- Control register lock sequence
- Configuration bit select lock

12.3.6.1 Control Register Lock

Under normal operation, writes to the RPnR and [*pin name*]R registers are not allowed. Attempted writes appear to execute normally, but the contents of the registers remain unchanged. To change these registers, they must be unlocked in hardware. The register lock is controlled by the IOLOCK Configuration bit (CFGCON<13>). Setting IOLOCK prevents writes to the control registers; clearing IOLOCK allows writes.

To set or clear the IOLOCK bit, an unlock sequence must be executed. Refer to **Section 6. "Oscillator"** (DS60001112) in the *"PIC32 Family Reference Manual"* for details.

12.3.6.2 Configuration Bit Select Lock

As an additional level of safety, the device can be configured to prevent more than one write session to the RPnR and [*pin name*]R registers. The IOL1WAY Configuration bit (DEVCFG3<29>) blocks the IOLOCK bit from being cleared after it has been set once. If IOLOCK remains set, the register unlock procedure does not execute, and the peripheral pin select control registers cannot be written to. The only way to clear the bit and re-enable peripheral remapping is to perform a device Reset.

In the default (unprogrammed) state, IOL1WAY is set, restricting users to one write session.

17.0 OUTPUT COMPARE

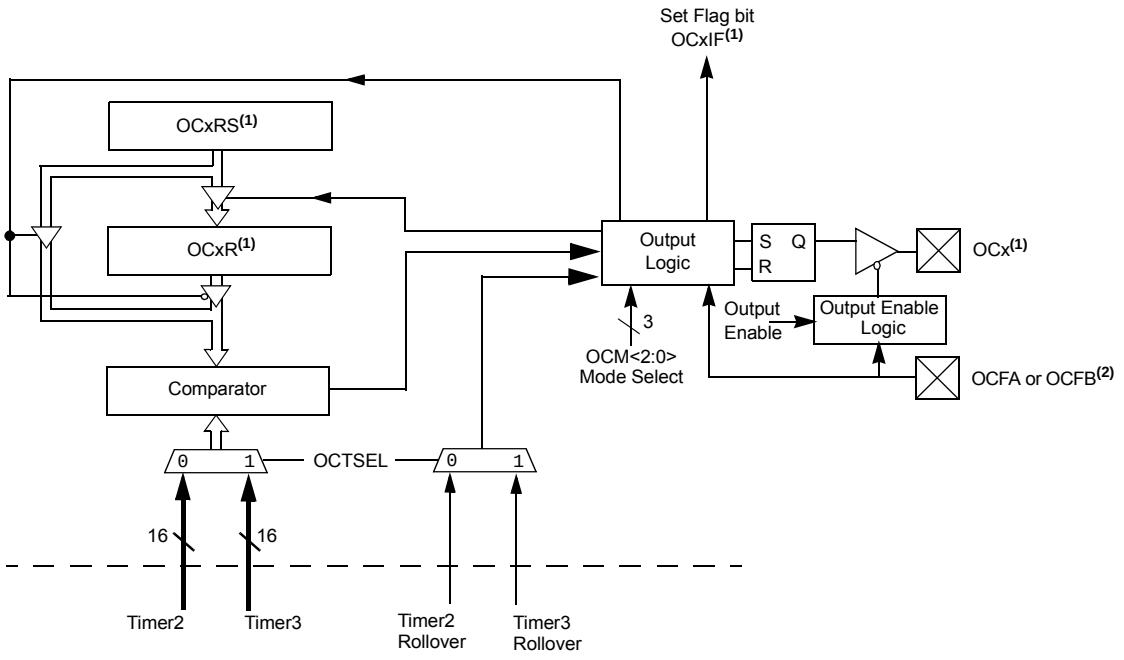
Note: This data sheet summarizes the features of the PIC32MX330/350/370/430/450/470 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 16. "Output Compare"** (DS60001111), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

The Output Compare module is used to generate a single pulse or a train of pulses in response to selected time base events. For all modes of operation, the Output Compare module compares the values stored in the OCxR and/or the OCxRS registers to the value in the selected timer. When a match occurs, the Output Compare module generates an event based on the selected mode of operation.

The following are key features of this module:

- Multiple Output Compare modules in a device
- Programmable interrupt generation on compare event
- Single and Dual Compare modes
- Single and continuous output pulse generation
- Pulse-Width Modulation (PWM) mode
- Hardware-based PWM Fault detection and automatic output disable
- Can operate from either of two available 16-bit time bases or a single 32-bit time base

FIGURE 17-1: OUTPUT COMPARE MODULE BLOCK DIAGRAM



Note 1: Where 'x' is shown, reference is made to the registers associated with the respective output compare channels, 1 through 5.

2: The OCFA pin controls the OC1-OC4 channels. The OCFB pin controls the OC5 channel.

REGISTER 18-2: SPIxCON2: SPI CONTROL REGISTER 2

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	SPISGNEXT	—	—	FRMERREN	SPIROVEN	SPITUREN	IGNROV	IGNTUR
7:0	R/W-0	U-0	U-0	U-0	R/W-0	U-0	R/W-0	R/W-0
	AUDEN(1)	—	—	—	AUDMONO(1,2)	—	AUDMOD<1:0>(1,2)	

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15 **SPISGNEXT:** Sign Extend Read Data from the RX FIFO bit
- 1 = Data from RX FIFO is sign extended
- 0 = Data from RX FIFO is not sign extened

bit 14-13 **Unimplemented:** Read as '0'

bit 12 **FRMERREN:** Enable Interrupt Events via FRMERR bit
- 1 = Frame Error overflow generates error events
- 0 = Frame Error does not generate error events

bit 11 **SPIROVEN:** Enable Interrupt Events via SPIROV bit
- 1 = Receive overflow generates error events
- 0 = Receive overflow does not generate error events

bit 10 **SPITUREN:** Enable Interrupt Events via SPITUR bit
- 1 = Transmit Underrun Generates Error Events
- 0 = Transmit Underrun Does Not Generates Error Events

bit 9 **IGNROV:** Ignore Receive Overflow bit (for Audio Data Transmissions)
- 1 = A ROV is not a critical error; during ROV data in the fifo is not overwritten by receive data
- 0 = A ROV is a critical error which stop SPI operation

bit 8 **IGNTUR:** Ignore Transmit Underrun bit (for Audio Data Transmissions)
- 1 = A TUR is not a critical error and zeros are transmitted until the SPIxTXB is not empty
- 0 = A TUR is a critical error which stop SPI operation

bit 7 **AUDEN:** Enable Audio CODEC Support bit(1)
- 1 = Audio protocol is enabled
- 0 = Audio protocol is disabled

bit 6-5 **Unimplemented:** Read as '0'

bit 3 **AUDMONO:** Transmit Audio Data Format bit(1,2)
- 1 = Audio data is mono (Each data word is transmitted on both left and right channels)
- 0 = Audio data is stereo

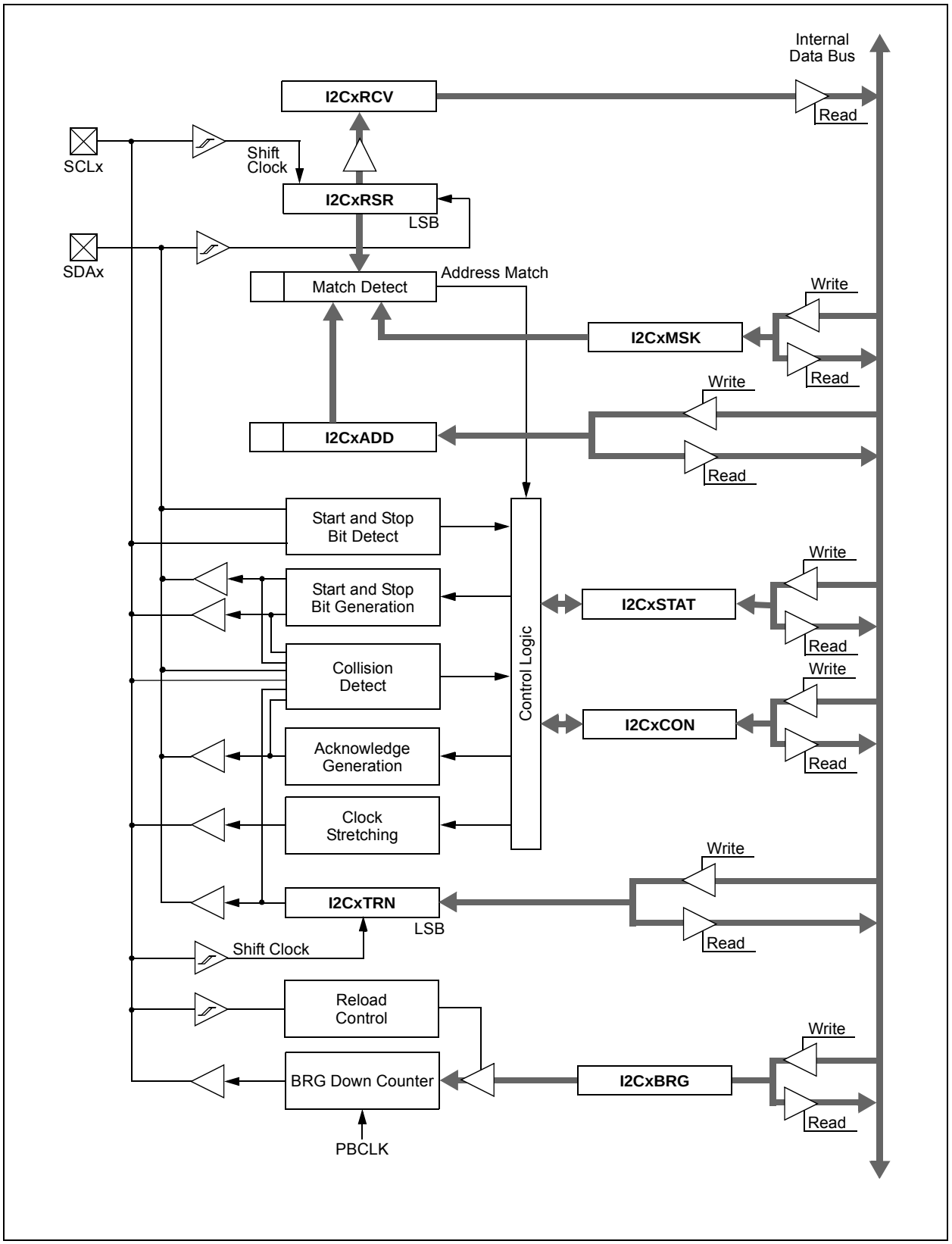
bit 2 **Unimplemented:** Read as '0'

bit 1-0 **AUDMOD<1:0>:** Audio Protocol Mode bit(1,2)
- 11 = PCM/DSP mode
- 10 = Right Justified mode
- 01 = Left Justified mode
- 00 = I^2S mode

Note 1: This bit can only be written when the ON bit = 0.

2: This bit is only valid for AUDEN = 1.

FIGURE 19-1: I²C BLOCK DIAGRAM



REGISTER 22-3: RTCTIME: RTC TIME VALUE REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
	HR10<3:0>				HR01<3:0>			
23:16	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
	MIN10<3:0>				MIN01<3:0>			
15:8	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
	SEC10<3:0>				SEC01<3:0>			
7:0	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-28 **HR10<3:0>:** Binary-Coded Decimal Value of Hours bits, 10s place digits; contains a value from 0 to 2

bit 27-24 **HR01<3:0>:** Binary-Coded Decimal Value of Hours bits, 1s place digit; contains a value from 0 to 9

bit 23-20 **MIN10<3:0>:** Binary-Coded Decimal Value of Minutes bits, 10s place digits; contains a value from 0 to 5

bit 19-16 **MIN01<3:0>:** Binary-Coded Decimal Value of Minutes bits, 1s place digit; contains a value from 0 to 9

bit 15-12 **SEC10<3:0>:** Binary-Coded Decimal Value of Seconds bits, 10s place digits; contains a value from 0 to 5

bit 11-8 **SEC01<3:0>:** Binary-Coded Decimal Value of Seconds bits, 1s place digit; contains a value from 0 to 9

bit 7-0 **Unimplemented:** Read as '0'

Note: This register is only writable when RTCWREN = 1 (RTCCON<3>).

31.0 ELECTRICAL CHARACTERISTICS

This section provides an overview of the PIC32MX330/350/370/430/450/470 electrical characteristics. Additional information will be provided in future revisions of this document as it becomes available.

Absolute maximum ratings for the PIC32MX330/350/370/430/450/470 devices are listed below. Exposure to these maximum rating conditions for extended periods may affect device reliability. Functional operation of the device at these or any other conditions, above the parameters indicated in the operation listings of this specification, is not implied.

Absolute Maximum Ratings

(See Note 1)

Ambient temperature under bias ..... -40°C to +105°C
Storage temperature ..... -65°C to +150°C
Voltage on V_{DD} with respect to V_{SS} ..... -0.3V to +4.0V
Voltage on any pin that is not 5V tolerant, with respect to V_{SS} **(Note 3)** ..... -0.3V to (V_{DD} + 0.3V)
Voltage on any 5V tolerant pin with respect to V_{SS} when $V_{DD} \geq 2.3V$ **(Note 3)** ..... -0.3V to +6.0V
Voltage on any 5V tolerant pin with respect to V_{SS} when $V_{DD} < 2.3V$ **(Note 3)** ..... -0.3V to +3.6V
Voltage on D+ or D- pin with respect to V_{USB3V3} ..... -0.3V to (V_{USB3V3} + 0.3V)
Voltage on V_{BUS} with respect to V_{SS} ..... -0.3V to +5.5V
Maximum current out of V_{SS} pin(s) ..... 200 mA
Maximum current into V_{DD} pin(s) **(Note 2)** ..... 200 mA
Maximum output current sourced/sunk by any 4x I/O pin ..... 15 mA
Maximum output current sourced/sunk by any 8x I/O pin ..... 25 mA
Maximum current sunk by all ports ..... 150 mA
Maximum current sourced by all ports **(Note 2)** ..... 150 mA

Note 1: Stresses above those listed under **"Absolute Maximum Ratings"** may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions, above those indicated in the operation listings of this specification, is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

2: Maximum allowable current is a function of device maximum power dissipation (see Table 31-2).

3: See the **"Device Pin Tables"** section for the 5V tolerant pins.

TABLE 31-8: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS (CONTINUED)

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symb.**	**Characteristics**	**Min.**	**Typ.(1)**	**Max.**	**Units**	**Conditions**
		Input Leakage Current (Note 3)					
DI50	IIL	I/O Ports	—	—	±1	μA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance
DI51		Analog Input Pins	—	—	±1	μA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance
DI55		$\overline{MCLR}$(2)	—	—	±1	μA	VSS ≤ VPIN ≤ VDD
DI56		OSC1	—	—	±1	μA	VSS ≤ VPIN ≤ VDD, XT and HS modes
DI60a	IICL	**Input Low Injection Current**	0	—	-5(7,10)	mA	Pins with Analog functions. Exceptions: [N/A] = 0 mA max
							Digital 5V tolerant designated pins. Exceptions: [N/A] = 0 mA max
							Digital non-5V tolerant designated pins. Exceptions: [N/A] = 0 mA max

Note 1: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

2: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

4: This parameter is characterized, but not tested in manufacturing.

5: See the **"Device Pin Tables"** section for the 5V tolerant pins.

6: The VIH specifications are only in relation to externally applied inputs, and not with respect to the user-selectable internal pull-ups. External open drain input signals utilizing the internal pull-ups of the PIC32 device are guaranteed to be recognized only as a logic "high" internally to the PIC32 device, provided that the external load does not exceed the minimum value of ICNPU. For External "input" logic inputs that require a pull-up source, to guarantee the minimum VIH of those components, it is recommended to use an external pull-up resistor rather than the internal pull-ups of the PIC32 device.

7: VIL source < (VSS - 0.3). Characterized but not tested.

8: VIH source > (VDD + 0.3) for non-5V tolerant pins only.

9: Digital 5V tolerant pins do not have an internal high side diode to VDD, and therefore, cannot tolerate any "positive" input injection current.

10: Injection currents > | 0 | can affect the ADC results by approximately 4 to 6 counts (i.e., VIH Source > (VDD + 0.3) or VIL source < (VSS - 0.3)).

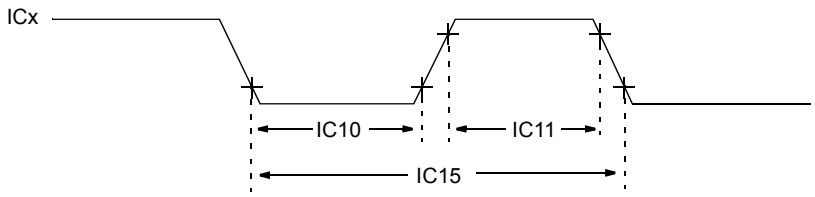
11: Any number and/or combination of I/O pins not excluded under IICL or IICH conditions are permitted provided the "absolute instantaneous" sum of the input injection currents from all pins do not exceed the specified limit. If **Note 7**, IICL = (((Vss - 0.3) - VIL source) / Rs). If **Note 8**, IICH = ((IICH source - (VDD + 0.3)) / RS). RS = Resistance between input source voltage and device pin. If (VSS - 0.3) ≤ VSOURCE ≤ (VDD + 0.3), injection current = 0.

TABLE 31-25: TIMER2, 3, 4, 5 EXTERNAL CLOCK TIMING REQUIREMENTS

AC CHARACTERISTICS				Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics(1)**		**Min.**	**Max.**	**Units**	**Conditions**	
TB10	TTXH	TxCK High Time	Synchronous, with prescaler	[(12.5 ns or 1 TPB)/N] + 25 ns	—	ns	Must also meet parameter TB15	N = prescale value (1, 2, 4, 8, 16, 32, 64, 256)
TB11	TTXL	TxCK Low Time	Synchronous, with prescaler	[(12.5 ns or 1 TPB)/N] + 25 ns	—	ns	Must also meet parameter TB15	
TB15	TTXP	TxCK Input Period	Synchronous, with prescaler	[(Greater of [(25 ns or 2 TPB)/N] + 30 ns	—	ns	VDD > 2.7V	
				[(Greater of [(25 ns or 2 TPB)/N] + 50 ns	—	ns	VDD < 2.7V	
TB20	TCKEXTMRL	Delay from External TxCK Clock Edge to Timer Increment		—	1	TPB	—	

Note 1: These parameters are characterized, but not tested in manufacturing.

FIGURE 31-7: INPUT CAPTURE (CAPx) TIMING CHARACTERISTICS



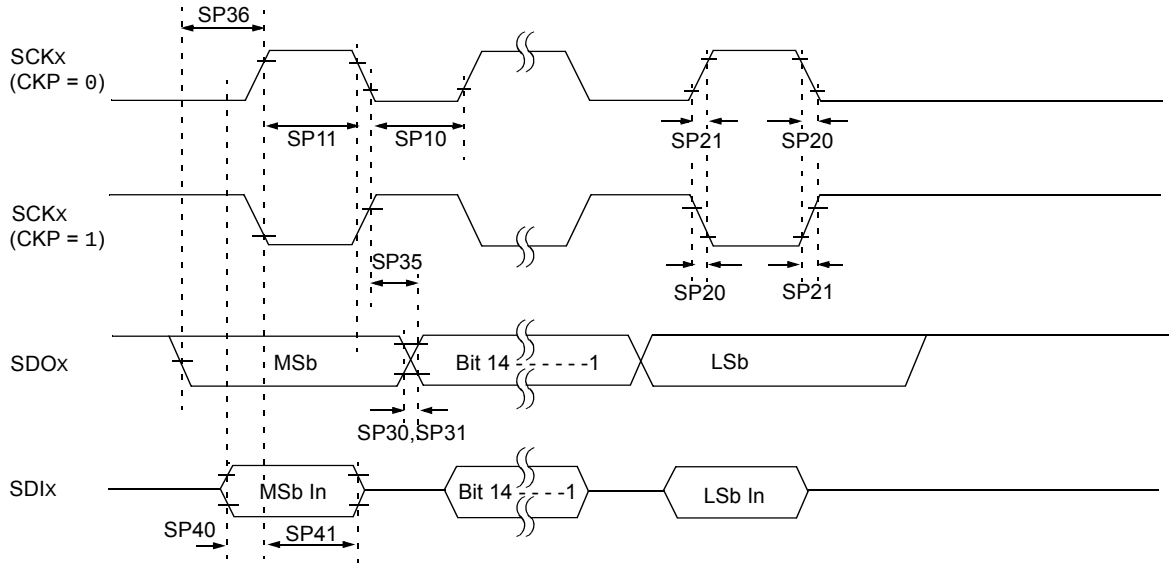
Note: Refer to Figure 31-1 for load conditions.

TABLE 31-26: INPUT CAPTURE MODULE TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics(1)**	**Min.**	**Max.**	**Units**	**Conditions**	
IC10	TCCL	ICx Input Low Time	[(12.5 ns or 1 TPB)/N] + 25 ns	—	ns	Must also meet parameter IC15.	N = prescale value (1, 4, 16)
IC11	TCCH	ICx Input High Time	[(12.5 ns or 1 TPB)/N] + 25 ns	—	ns	Must also meet parameter IC15.	
IC15	TCCP	ICx Input Period	[(25 ns or 2 TPB)/N] + 50 ns	—	ns	—	

Note 1: These parameters are characterized, but not tested in manufacturing.

FIGURE 31-11: SPIx MODULE MASTER MODE (CKE = 1) TIMING CHARACTERISTICS



Note: Refer to Figure 31-1 for load conditions.

TABLE 31-30: SPIx MODULE MASTER MODE (CKE = 1) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP10	TscL	SCKx Output Low Time **(Note 3)**	Tsck/2	—	—	ns	—
SP11	TscH	SCKx Output High Time **(Note 3)**	Tsck/2	—	—	ns	—
SP20	TscF	SCKx Output Fall Time **(Note 4)**	—	—	—	ns	See parameter DO32
SP21	TscR	SCKx Output Rise Time **(Note 4)**	—	—	—	ns	See parameter DO32
SP30	TdoF	SDOx Data Output Fall Time **(Note 4)**	—	—	—	ns	See parameter DO32
SP31	TdoR	SDOx Data Output Rise Time **(Note 4)**	—	—	—	ns	See parameter DO31
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	—	15	ns	VDD > 2.7V
			—	—	20	ns	VDD < 2.7V
SP36	TdoV2sc, TdoV2scL	SDOx Data Output Setup to First SCKx Edge	15	—	—	ns	—
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	15	—	—	ns	VDD > 2.7V
			20	—	—	ns	VDD < 2.7V
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	15	—	—	ns	VDD > 2.7V
			20	—	—	ns	VDD < 2.7V

Note 1: These parameters are characterized, but not tested in manufacturing.

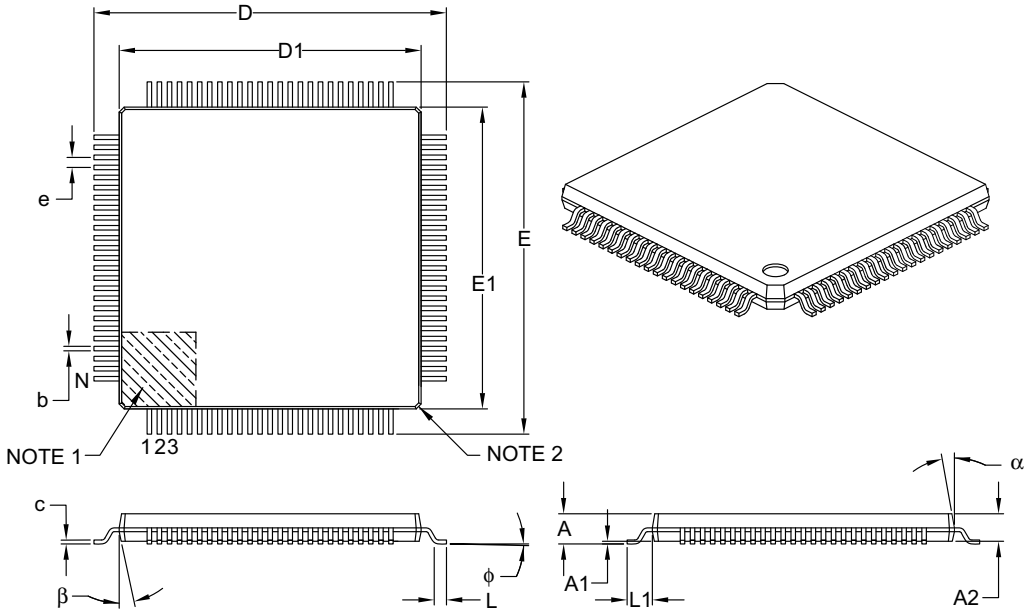
2: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: The minimum clock period for SCKx is 40 ns. Therefore, the clock generated in Master mode must not violate this specification.

4: Assumes 50 pF load on all SPIx pins.

100-Lead Plastic Thin Quad Flatpack (PT) – 12x12x1 mm Body, 2.00 mm [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N		100	
Lead Pitch	e		0.40 BSC	
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	–	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1		1.00 REF	
Foot Angle	ϕ	0°	3.5°	7°
Overall Width	E		14.00 BSC	
Overall Length	D		14.00 BSC	
Molded Package Width	E1		12.00 BSC	
Molded Package Length	D1		12.00 BSC	
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.13	0.18	0.23
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-100B

Revision C (October 2013)

This revision includes the following updates, as listed in Table A-2.

TABLE A-2: MAJOR SECTION UPDATES

Section	Update Description
"32-bit Microcontrollers (up to 512 KB Flash and 128 KB SRAM) with Audio/Graphics/Touch (HMI), USB, and Advanced Analog"	The Operating Conditions and Core sections were updated in support of 100 MHz (-40ºC to +85ºC) devices. Added Notes 2 and 3 regarding the conductive thermal pad to the 124-pin VTLA pin diagrams.
2.0 "Guidelines for Getting Started with 32-bit MCUs"	Updated the recommended minimum connection (see Figure 2-1). Added **2.10 "Sosc Design Recommendation"**.
20.0 "Parallel Master Port (PMP)"	Updated the Parallel Port Control register, PMCON (see Register 20-1). Updated the Parallel Port Mode register, PMMODE (see Register 20-2). Updated the Parallel Port Pin Enable register, PMAEN (see Register 20-4).
30.0 "Electrical Characteristics"	Removed Note 4 from the Absolute Maximum Ratings. The maximum frequency for parameter DC5 In Operating MIPS vs. Voltage was changed to 100 MHz (see Table 30-1). Parameter DC25a was added to DC Characteristics: Operating Current (IDD) (see Table 30-5). Parameter DC34c was added to DC Characteristics: Idle Current (IIDLE) (see Table 30-5). Added parameters for PIC32MX370/470 devices and removed Note 5 from DC Characteristics: Power-Down Current (IPD) (see Table 30-7). Updated the Minimum, Typical, and Maximum values and added a reference to Note 3 for parameter DI30 (ICNPU) in DC Characteristics: I/O Pin Input Specifications (see Table 30-8). The SYSCLK values for all required Flash Wait states were updated (see Table 30-13). Added parameter DO50A (CSOSC) to the Capacitive Loading Requirements on Output Pins (see Table 30-16). Updated the maximum values for parameter OS10, and the Characteristics definition of parameter OS42 (GM) in the External Clock Timing Characteristics (see Table 30-17).
31.0 "DC and AC Device Characteristics Graphs"	Updated the IPD, IIDLE, and IDD graphs, and added new graphs for the PIC32MX370/470 devices (see Figure 31-5 through Figure 31-13).